





P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
-20V	$75m\Omega @ V_{GS} = -4.5V$	-3.8A
-200	137mΩ @ V_{GS} = -2.5 V	-2.8A

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, which makes it ideal for high-efficiency power management applications.

Applications

- General Purpose Interfacing Switch
- Power Management Functions





TSOT26

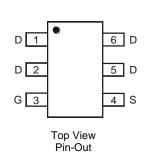
Top View

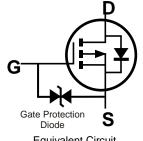
Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- **ESD Protected Gate**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: TSOT26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.015 grams (Approximate)





Equivalent Circuit

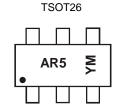
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP2075UVT-7	TSOT26	3000/Tape & Reel
DMP2075UVT-13	TSOT26	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



AR5 = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: F = 2018) M = Month (ex: 9 = September)

Date Code Key

Year	2018	2019	20	020	2021	2022	2	2023	2024	202	25	2026
Code	F	G		Н	I	J		K	L	N	1	N
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	V	
Gate-Source Voltage	V_{GSS}	±8	V
Continuous Drain Current (Note 6) V _{GS} = -4.5V	Ι _D	-3.8 -3.0	А
Maximum Continuous Body Diode Forward Current (Is	-2.1	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	-25	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P _D	1.2	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ heta JA}$	105	°C/W
Total Power Dissipation (Note 6)	P _D	1.6	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{ heta JA}$	77	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

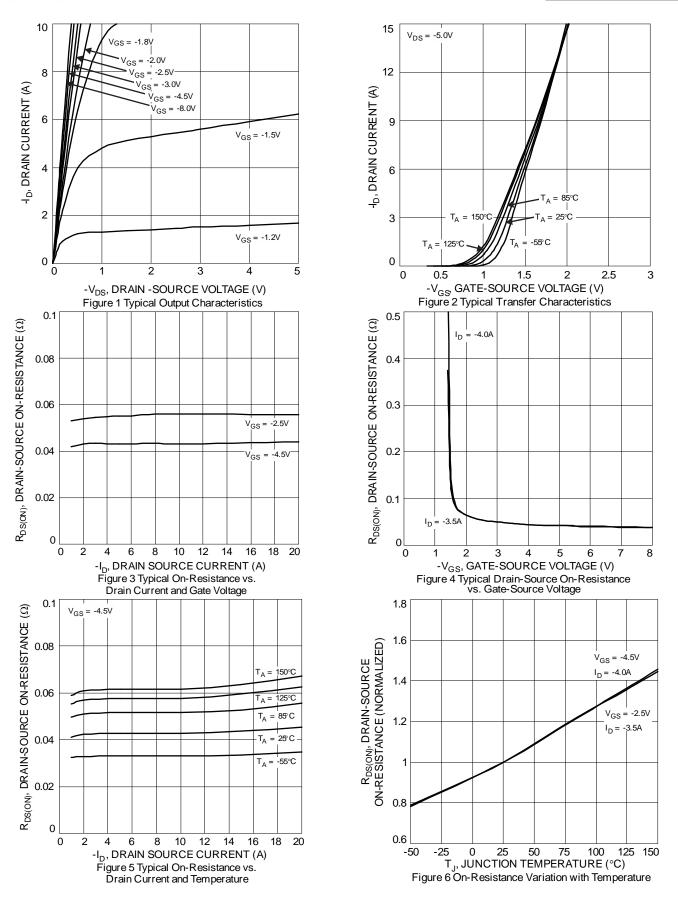
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_		-1	μA	$V_{DS} = -20V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 8.0V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	$V_{GS(TH)}$	-0.3	_	-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Statia Drain Sauras On Basistanas	0	_	_	75	mΩ	$V_{GS} = -4.5V$, $I_D = -4.0A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	_	137	11122	$V_{GS} = -2.5V, I_D = -3.5A$	
Diode Forward Voltage	V _{SD}	_		-1.2	V	V _{GS} = 0V, I _S = -1.0A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	_	642		pF		
Output Capacitance	Coss	_	98	_	pF	V _{DS} = -10V, V _{GS} = 0V f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	_	87	_	pF	1 - 1.0WH12	
Gate Resistance	R_g	_	26.5	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge	Qg	_	8.8	_	nC		
Gate-Source Charge	Q _{gs}	_	0.9	_	nC	$V_{GS} = -4.5V, V_{DS} = -10V$ $I_{D} = -4A$	
Gate-Drain Charge	Q _{gd}	_	2.9	_	nC	104/	
Turn-On Delay Time	t _{D(ON)}	_	5.5		ns		
Turn-On Rise Time	t _R	_	22.6	_	ns	$V_{DS} = -10V, V_{GS} = -4.5V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	34.1	1	ns	$R_D = 2.5\Omega$, $R_G = 3.0\Omega$, $I_D = -1A$	
Turn-Off Fall Time	t _F	_	34.3	-	ns		
Reverse Recovery Time	t _{RR}	_	13		ns	$I_F = -1.0A$, $di/dt = 100A/\mu s$	
Reverse Recovery Charge	Q _{RR}	_	3.3	_	nC	$I_F = -1.0A$, $di/dt = 100A/\mu s$	

Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to product testing.

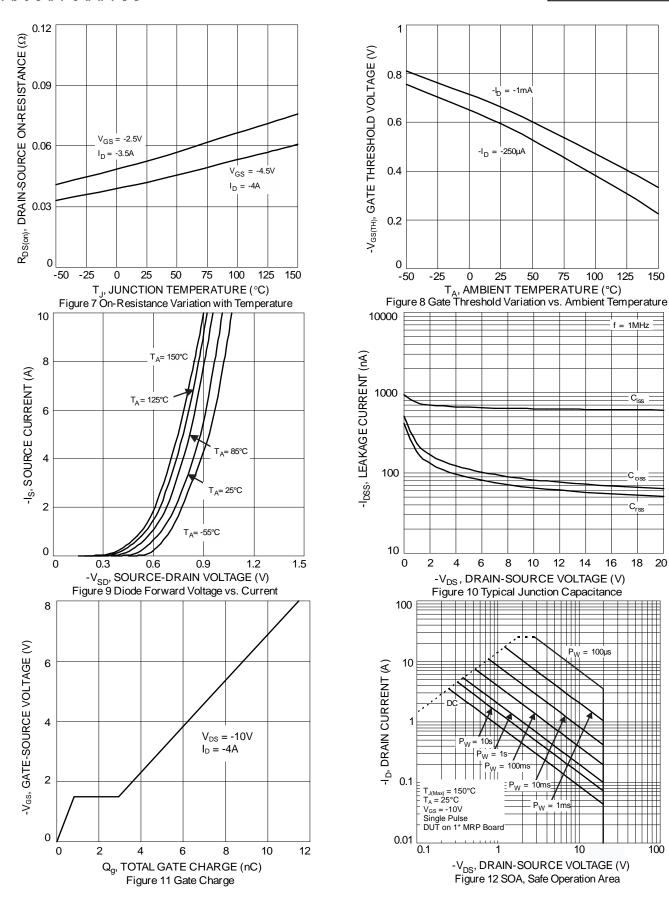




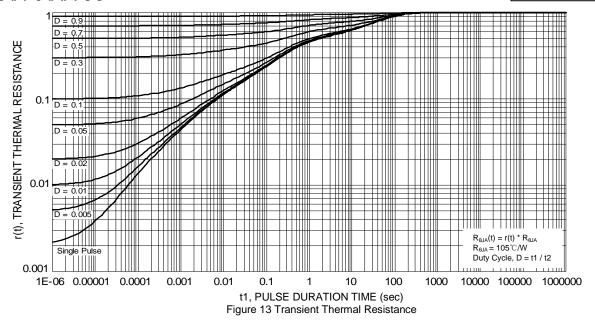
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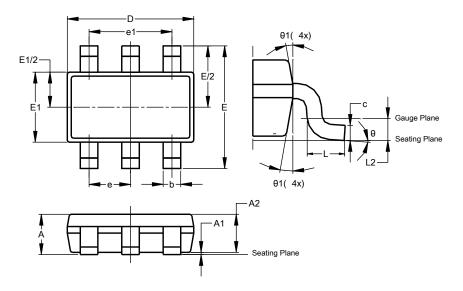




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TSOT26

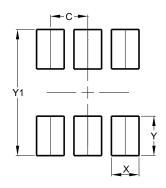


	TSOT26						
Dim	Min	Max	Тур				
Α	-	1.00	_				
A1	0.010	0.100	-				
A2	0.840	0.900	_				
D	2.800	3.000	2.900				
Е	2	.800 BS	C				
E1	1.500	1.700	1.600				
b	0.300	0.450	1				
С	0.120	1					
е	0.950 BSC						
e1	1	1.900 BSC					
L	0.30 0.50 -		1				
L2	0.250 BSC						
θ	0°	8°	4°				
θ1	4° 12° –		-				
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

TSOT26



Dimensions	Value (in mm)
С	0.950
Х	0.700
Y	1.000
Y1	3.199



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